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IN THE CLAIMS:

1. (currently amended) A center-electrode assembly comprising:
a ferrite;
center-electrode patterns and insulating films deposited on the top surface of the ferrite;
a conductive pattern formed on the bottom surface of the ferrite; and
connecting electrodes directly formed on margins of the ferrite; wherein
the connecting electrodes electrically connect the center-electrode patterns and
the conductive pattern; and
said connecting electrodes are comprised of at least one of a plated conductive material, a printed conductive material, a sputtered conductive material, a vapor deposited conductive material and an applied paste conductive material formed directly on the margins of the ferrite.
2. (original) A nonreciprocal circuit device comprising:
a permanent magnet;
a center-electrode assembly according to Claim 1 to which a direct-current magnetic field is applied by the permanent magnet; and
a metallic case accommodating the permanent magnet and the center-electrode assembly.
3. (original) A communication apparatus comprising a nonreciprocal circuit device according to Claim 2, and connected thereto, at least one of a transmitting circuit and a reception circuit.
4. (original) A communication apparatus comprising a center-electrode assembly according to Claim 1, and connected thereto, at least one of a transmission circuit and a reception circuit.

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5. (currently amended) A method for manufacturing a center-electrode assembly comprising the steps of:

forming through-holes in a ferrite mother board:

alternately depositing a center-electrode pattern and an insulating film on the top surface of the ferrite mother board, and forming a conductive pattern on the back surface of the ferrite mother board; and

cutting a center-electrode assembly from the ferrite mother board by cutting the ferrite mother board at intervals of a predetermined size; and

forming connecting electrodes in the through-holes in the center electrode assembly by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method and a conductive paste applying method to electrically connect, the center-electrode patterns formed on the top surface and the conductive pattern formed on the back surface being electrically connected via connecting electrodes formed in the through-holes in the center electrode assembly.

6. (previously added) A center-electrode assembly according to claim 1, wherein the connecting electrodes are formed on grooves formed in the margins of the ferrite.

7. (previously added) A center-electrode assembly according to claim 1, further comprising:

ports directly formed on the margins of the ferrite; wherein
the ports are electrically connected with the connecting electrodes via the center-
electrode patterns

8. (previously added) A center-electrode assembly according to claim 7, further comprising:

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gaps formed on the bottom surface of the ferrite; wherein
the gaps are provided between ends of the ports and an end of the conductive
pattern.

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9. (withdrawn) A center-electrode assembly according to claim 1, further comprising:

ports directly formed on the upper surface of the ferrite; wherein
the ports are electrically connected with the connecting electrodes via the center-
electrode patterns.

10. (currently amended) A center-electrode assembly comprising:
a ferrite;
center-electrode patterns and insulating films laminated on the top surface of the
ferrite;
a conductive pattern formed on the bottom surface of the ferrite, and
connecting electrodes formed in external peripheral portions of the ferrite;
wherein

the connecting electrodes electrically connect the center-electrode patterns and
the conductive pattern; and

said connecting electrodes are comprised of at least one of a plated conductive
material, a printed conductive material, a sputtered conductive material, a vapor
deposited conductive material and an applied paste conductive material formed directly
on the margins of the ferrite.